

H5N1506P

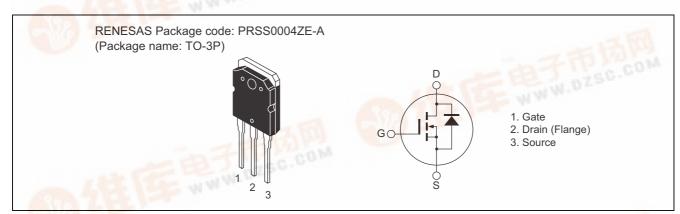
Silicon N Channel MOS FET High Speed Power Switching

REJ03G0389-0200 Rev.2.00 Jul 03, 2006

Features

- Low on-resistance
- Low leakage current
- High speed switching

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to Source voltage	V _{DSS}	150	V
Gate to Source voltage	V _{GSS}	±30	V
Drain current	G I _D	98	Α
Drain peak current	I _{D (pulse)} Note1	294	Α
Body-Drain diode reverse Drain current	I _{DR}	98	А
Body-Drain diode reverse Drain peak current	I _{DR (pulse)} Note1	294	A
Avalanche current	I _{AP} Note3	48	A
Avalanche energy	E _{AR} Note3	172	mJ
Channel dissipation	Pch Note2	150	W
Channel to case thermal impedance	θch-c	0.833	°C/W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

2. Value at Tc = 25°C Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

- 3. STch = 25° C, Tch $\leq 150^{\circ}$ C



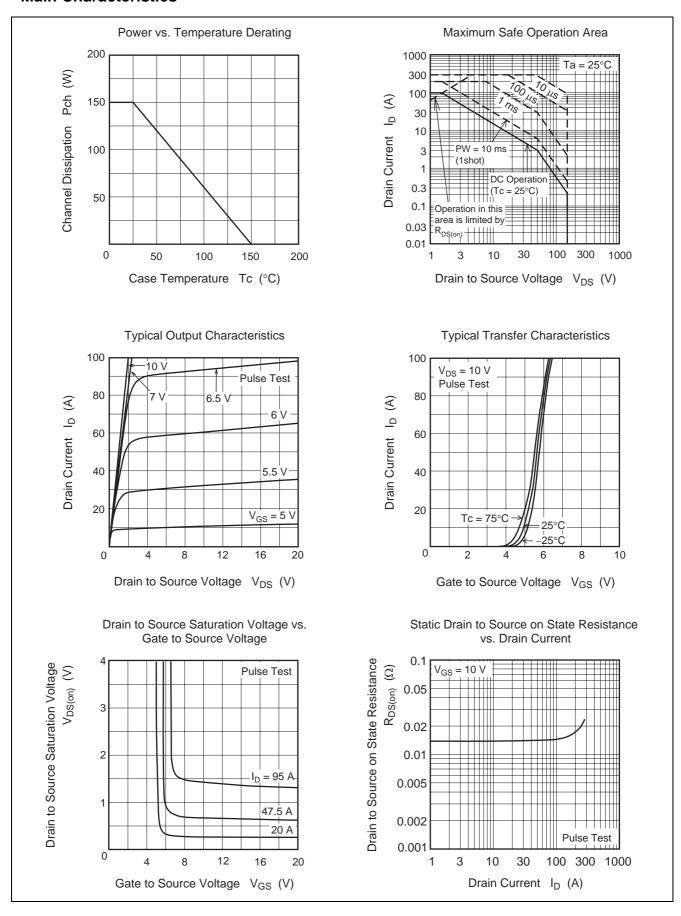
Electrical Characteristics

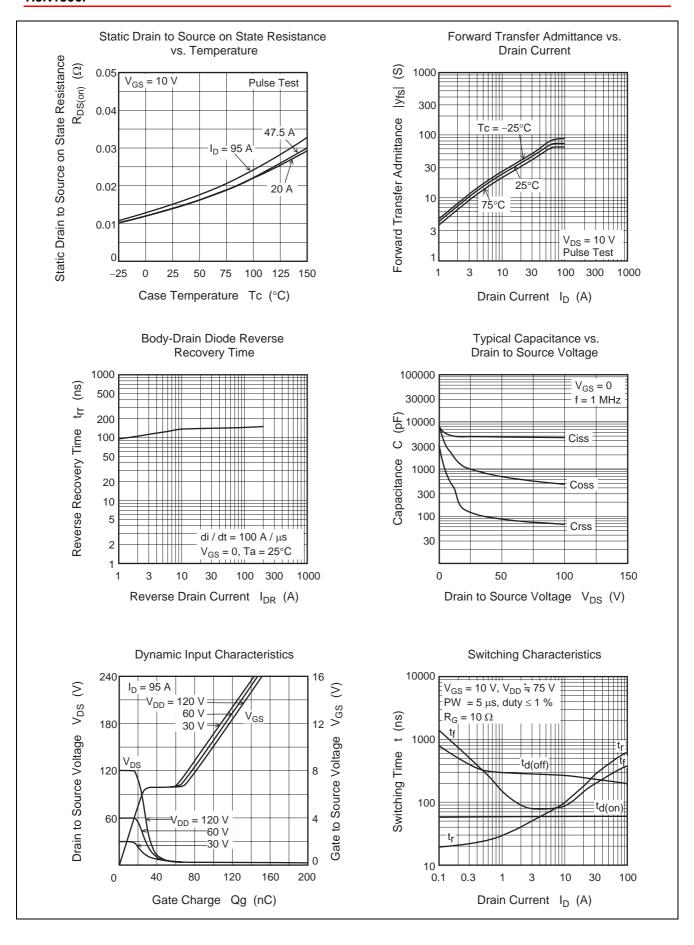
 $(Ta = 25^{\circ}C)$

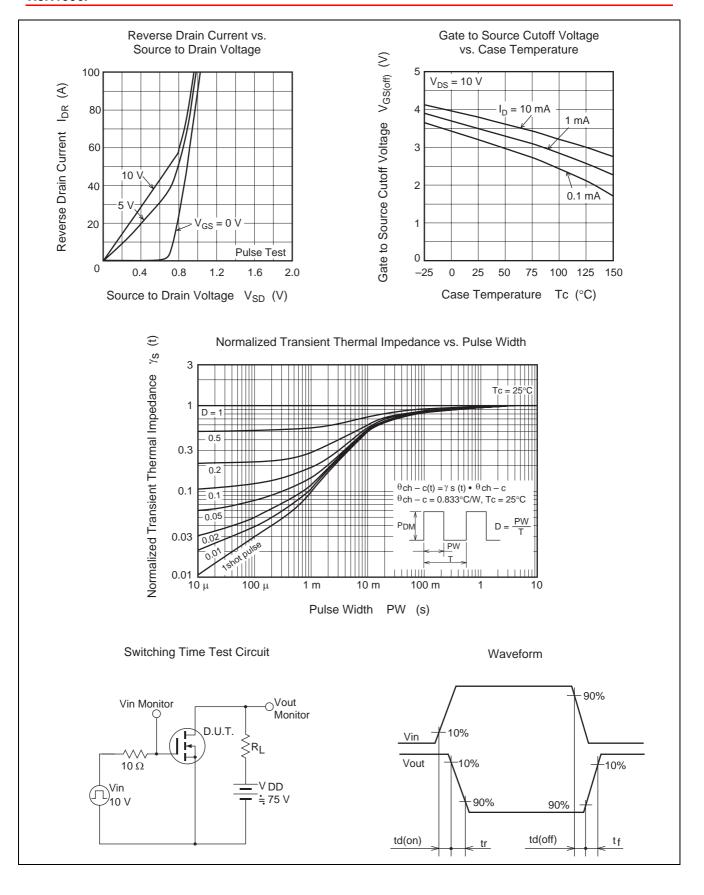
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to Source breakdown voltage	$V_{(BR)DSS}$	150	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Zero Gate voltage Drain current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 150 \text{ V}, V_{GS} = 0$
Gate to Source leak current	I _{GSS}	_	_	±0.1	μΑ	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0$
Gate to Source cutoff voltage	$V_{GS(off)}$	3.0	_	4.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Forward transfer admittance	yfs	36	60	_	S	$I_D = 47.5 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note4}}$
Static Drain to Source on state resistance	R _{DS(on)}	_	0.014	0.016	Ω	$I_D = 47.5 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note4}}$
Input capacitance	Ciss	_	4900	_	pF	V _{DS} = 25 V
Output capacitance	Coss	_	1000	_	pF	V _{GS} = 0 f = 1 MHz
Reverse transfer capacitance	Crss	_	120	_	pF	
Turn-on delay time	t _{d(on)}	_	60	_	ns	I _D = 47.5 A
Rise time	t _r	_	380	_	ns	$V_{GS} = 10 \text{ V}$ $R_L = 1.58 \Omega$ $Rg = 10 \Omega$
Turn-off delay time	t _{d(off)}	_	220	_	ns	
Fall time	t _f	_	250	_	ns	
Total Gate charge	Qg	_	100	_	nC	V _{DD} = 120 V
Gate to Source charge	Qgs	_	24	_	nC	V _{GS} = 10 V I _D = 95 A
Gate to Drain charge	Qgd	_	45	_	nC	
Body-Drain diode forward voltage	V_{DF}	_	1.0	1.5	V	$I_F = 95 \text{ A}, V_{GS} = 0^{\text{Note4}}$
Body-Drain diode reverse recovery time	trr		150	_	ns	$I_F = 95 \text{ A}, V_{GS} = 0$ $di_F/dt = 100 \text{ A}/\mu\text{s}$
Body-Drain diode reverse recovery charge	Qrr	_	1.0	_	μС	

Notes: 4. Pulse test

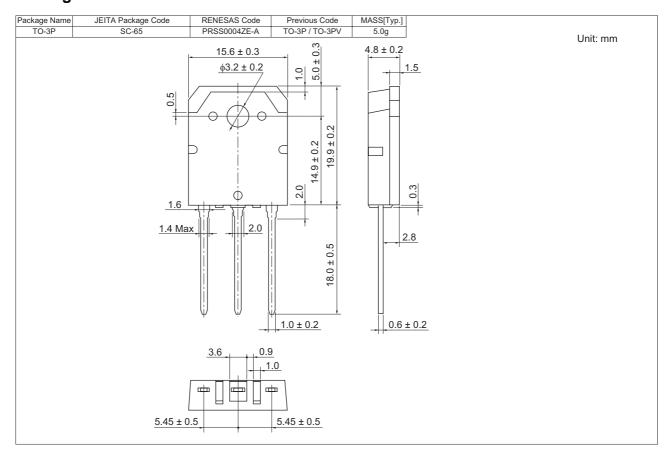
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
H5N1506P-E	360 pcs	Box (Tube)

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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Renesas Technology Malaysia Sdn. Bhd
Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia Tel: <603> 7955-9390, Fax: <603> 7955-9510

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